

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KOJI WATANABE	05/10/2016
MINORU TOYODA	04/15/2016
SATOSHI TOMITA	05/10/2016
TSUTOMU SUGINO	05/10/2016
DAICHI KIKUCHI	05/10/2016
HIROKI OSHIMA	05/10/2016
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14648031
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SIGNATURE:	/Laura Donnelley/
DATE SIGNED:	05/12/2016

Total Attachments: 2

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ASSIGNMENT - PATENT APPLICATION

WHEREAS, I/We, WATANABE Koji, TOYODA Minoru, TOMITA Satoshi, SUGINO Tsutomu, KIKUCHI Daichi, and OSHIMA Hiroki have invented certain new and useful improvements in

**LAYERED SOLDER MATERIAL FOR BONDING DISSIMILAR ELECTRODES, AND
METHOD FOR BONDING DISSIMILAR ELECTRODES TO ELECTRONIC
COMPONENTS**

for which an application for United States Letters Patent is being filed as the U.S. National Stage of International Application PCT/JP2013/081044, filed November 18, 2013, and claiming priority to Japanese Patent application No. 2012-263103 filed November 30, 2012; and

WHEREAS, Senju Metal Industry Co., Ltd. of 23, Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, JAPAN (hereinafter "Assignee") desires to acquire an interest in said improvements and in the Letters Patent to be obtained therefor;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are acknowledged, I/We hereby assign and transfer to Assignee, for the territory of the United States of America and all other countries, the entire right, title, and interest in and to said improvements and in and to said application and any Letters Patent that may be granted therefor in the United States and any other country including any division, continuation, substitute, renewal or reissue of said application or said Letters Patent.

I/We hereby agree to communicate to Assignee any facts known to me/us relating to said improvements, to testify as to the same in any interference or legal proceeding concerned therewith, to execute promptly and deliver to Assignee upon request any and all papers, instruments, declarations and affidavits required to apply for, obtain, maintain and enforce said Letters Patent, and generally to do everything necessary or desirable to vest and perfect title thereto in Assignee.

This assignment is binding upon me/us and my/our heirs, successors, and legal representatives, and shall inure to the benefit of Assignee, its successors, assigns and nominees.

I/We agree that no attorney/client or other fiduciary relationship exists between me/us and CHERNOFF, VILHAUER, MCCLUNG & STENZEL, LLP.
INVENTOR(S):


WATANABE Koji

May 10, 2016
Date

Minoru, Toyoda.
TOYODA Minoru

2016. 4/5
Date

Tomita Satoshi
TOMITA Satoshi

May 10, 2016
Date

Tsutomi Sugino
SUGINO Tsutomu

May 10, 2016
Date

Daichi Kikuchi
KIKUCHI Daichi

May 10, 2016
Date

Hiroki Oshima
OSHIMA Hiroki

May 10, 2016
Date